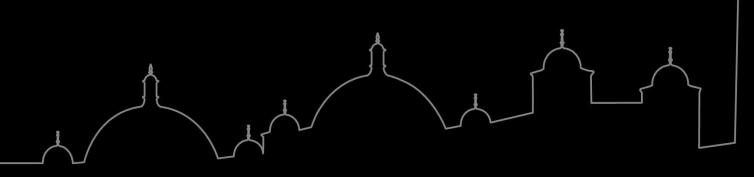


FPC Interface Board update

James Glover

EIC-UK WP1 meeting

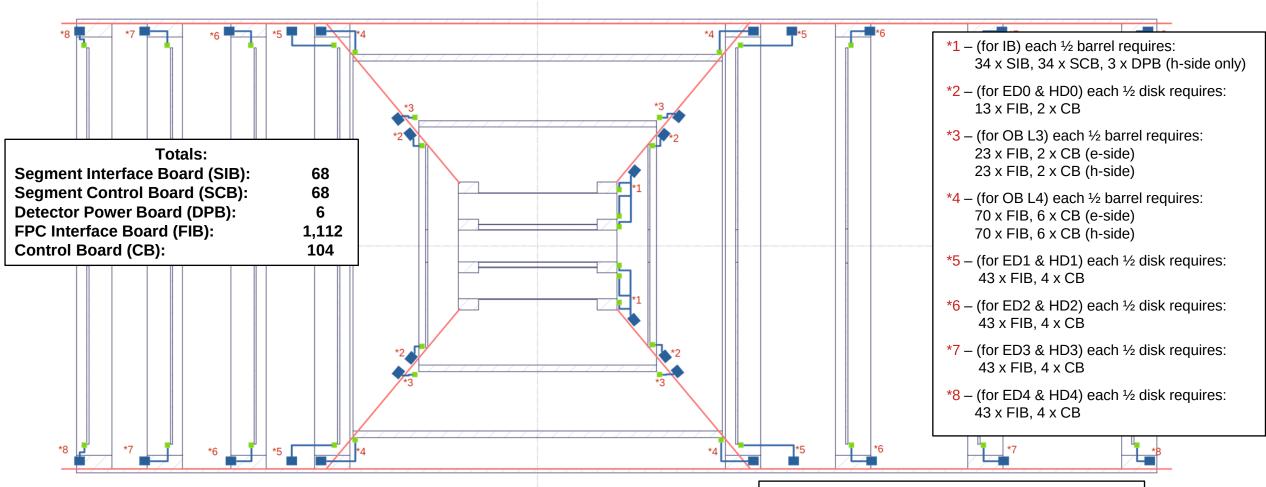
Wed, 8th October 2025



Approx SVT RDO board locations

ePIC UK

Work in progress



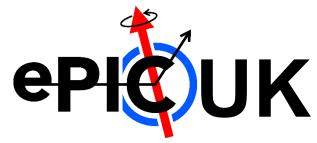


As reported in the Stony Brook Working Meeting

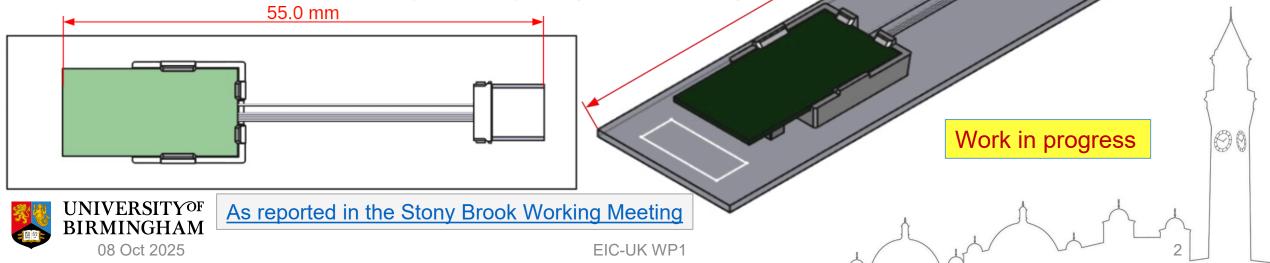
Carbon fibre support structure (tube and cone)

- Electronics boards (Interface Boards)
- Electronics boards (Control Boards/Power Boards)

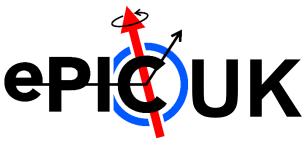
Approximate FIB dimensions



- Shortest possible total length (5.5 cm) that CERN will produce.
- Prevent damage to VTRx+ pigtail, by mounting total length on the FIB.
- Allow space to bond/solder FPC and Control Board connections to FIB.
- Keep the board narrower than 1 EIC-LAS.
- ~4 mm total package height (incl. PCB).

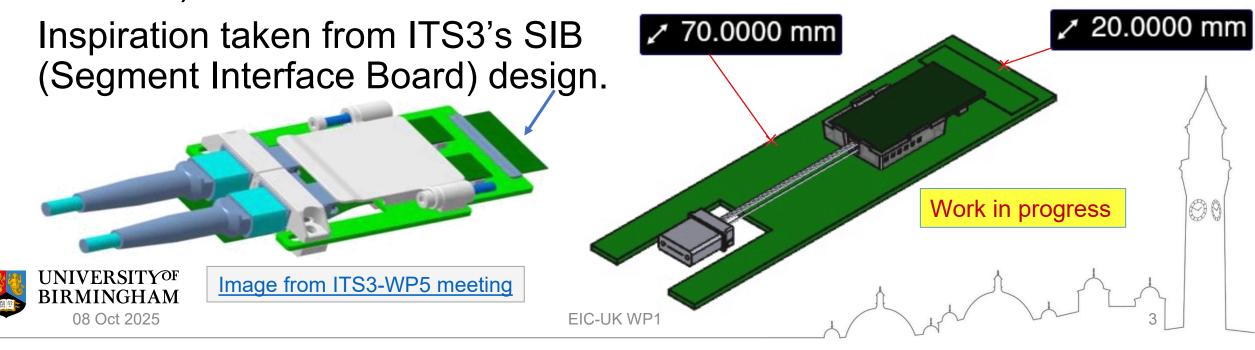


Basic FIB volume (for CAD models)

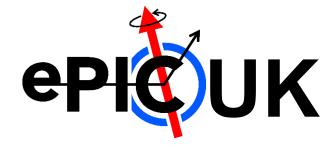


Already got larger, to accommodate the:

- Cut-out for the MT connector (and have extra PCB area for a connector clamp).
- ±2.5 mm of fibre length adjustment (the tolerance status by CERN).



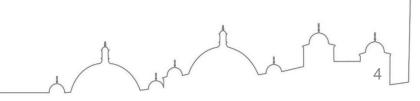
Additions to the design



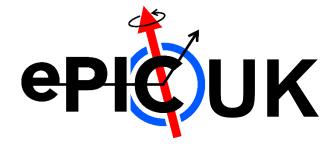
Additional elements needed to be included:

- Electrical connections from the Control Board (CB):
 - 2.5 V and 1.2 V power for the VTRx+ → 3 to 6 wires.
 - I²C for the VTRx+ \rightarrow 2 wires (if GND from power lines).
 - Reset and Disable line for the laser driver → 2 wires.
 - S/Cs for the FPC/EIC-LAS (via the AncASIC) → 3 wires.
- Serial powering lines (directly from the current source).
- MT to MTP adapter (for OTS fibre harnesses to be used).
- Optional CB to FIB connections:
 - VTRx+ RSSI current, VTRx+ thermistor, 1.2 and 2.5V sense wires.

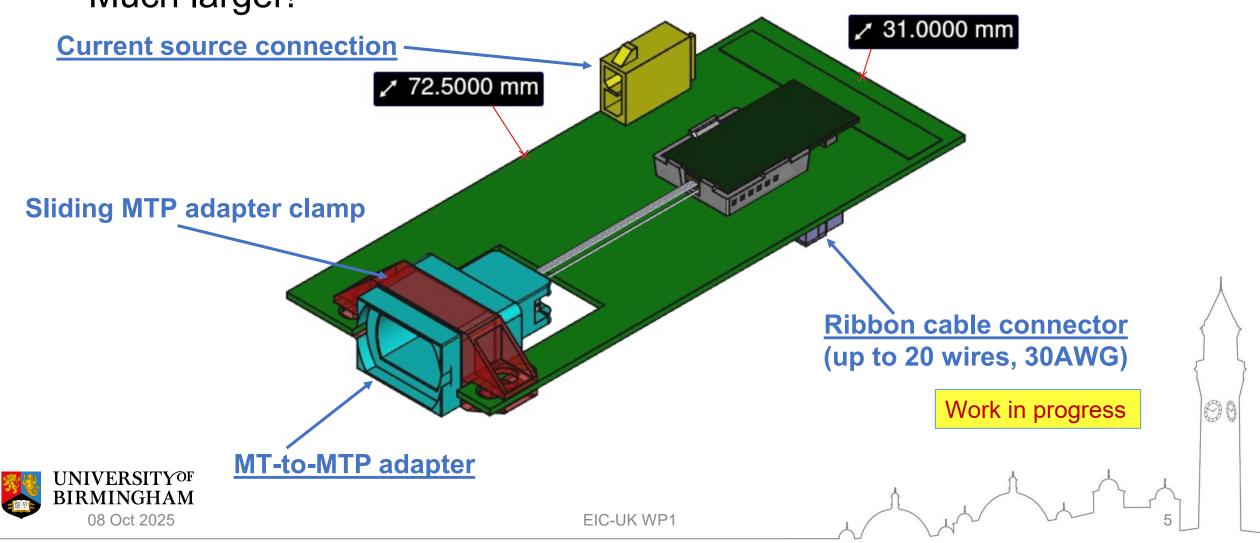




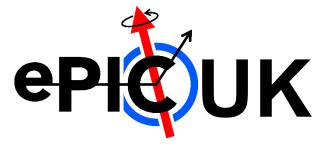
Current FIB



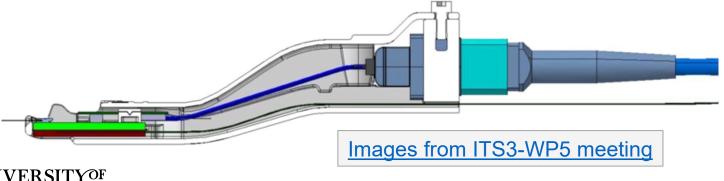
Much larger!



Possible optimisations

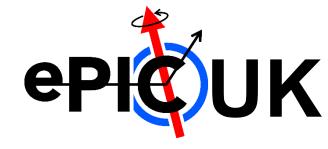


- Board width enables "Sliding MTP adapter clamp" and "Current source connection" to sit side-by-side.
 - Moving "Current source connection" back, beside the VTRx+ could enable board to narrow (2-5 mm).
- Board length is to support full length of VTRx+ fibre pigtail.
 - Custom 3D-printed fibre enclosure/MTP holder could reduce PCB footprint (similar to newer ITS3 SIB designs).





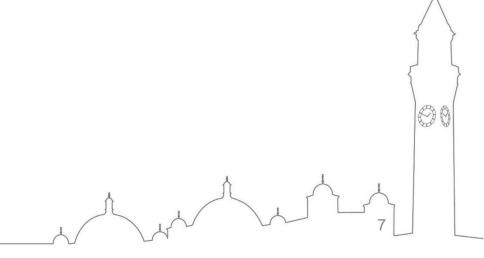
Summary



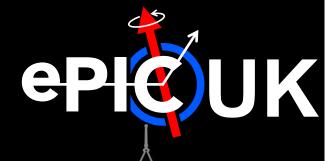
- Update to the FIBs are being considered.
- Considerations for actual # of connections needed per FIB.

- Adding realism and connectors.
- FIB is getting bulkier.



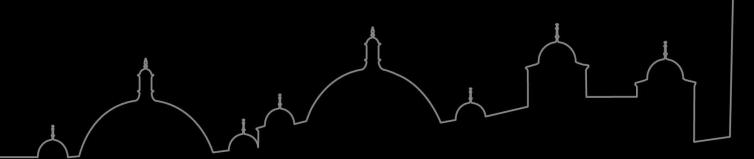




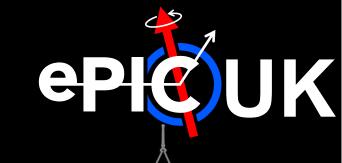


Thank you very much!

Any questions?







Additional (support) slides

